Applied Materials 300mm Epi HW Configurations

System Information

OEM Vendor:	Applied Materials
Vintage:	2010
Wafer Size:	300mm

EFEM

- AMAT 5.3x Factory Interface x1
- TDK Load Ports x2
- Yaskawa Robot x1
- Wafer Pre-Aligner x1

Main Frame

- ACP Mainframe x1
- Batch Load Locks x2
- Cooling Stations, ACP MF x2
- VHP robot, Single Arm x1
- Facility Tray x1
- Upper Frame, Cooling Module x1
- Gas panel remotes x1
- Chamber AC racks x1
- Touch screen UI, Roll-around stand x1

CHA – EPI 300

- Reduced Pressure (RP)
- Rotation Lift (pneumatic/motor)
- Gas Panel (MFC – Horiba STEC Z500, IGS)

MFC No.	Gas	Flow
1	H2	100 slm
2	H2	30 slm
3	HCL	500 sccm
4	PH3	500 sccm
5	HCL	20 slm
6	empty	n/a
7	DCS	500 sccm

CHC – EPI 300

- Reduced Pressure (RP)

- Rotation Lift (pneumatic/motor)
- Gas Panel (MFC – UNIT)

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